

## KSH47/50

### High Voltage and High Reliability **D-PAK for Surface Mount Applications**

- Lead Formed for Surface Mount Application (No Suffix)
  Straight Lead (I-PAK, "- I" Suffix)
- Electrically Similar to Popular TIP47 and TIP50



## **NPN Epitaxial Silicon Transistor**

### Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CBO</sub>	Collector-Emitter Voltage		
020	: KSH47	350	V
	: KSH50	500	V
V <sub>CEO</sub>	Collector-Emitter Voltage		
	: KSH47	250	V
	: KSH50	400	V
V <sub>EBO</sub>	Emitter-Base Voltage	5	V
I <sub>C</sub>	Collector Current (DC)		Α
I <sub>CP</sub>	Collector Current (Pulse)	2	Α
I <sub>B</sub>	Base Current	0.6	А
P <sub>C</sub>	Collector Dissipation (T <sub>C</sub> =25°C)	15	W
	Collector Dissipation (T <sub>a</sub> =25°C)	1.56	W
TJ	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	- 65 ~ 150	°C

### Electrical Characteristics T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
V <sub>CEO</sub> (sus)	* Collector-Emitter Sustaining Voltage				
	: KSH47	$I_C = 30 \text{mA}, I_B = 0$	250	-717	V
	: KSH50		400		V
I <sub>CEO</sub>	Collector Cut-off Current		100	Dr.	
020	: KSH47	$V_{CE} = 150V, I_{B} = 0$	All All	0.2	mA
	: KSH50	$V_{CE} = 300V, I_{B} = 0$		0.2	mA
I <sub>CES</sub>	Collector Cut-off Current	- W(6)			
	: KSH47	$V_{CE} = 350, V_{EB} = 0$		0.1	mA
	: KSH50	$V_{CE} = 500, V_{EB} = 0$		0.1	mA
I <sub>EBO</sub>	Emitter Cut-off Current	$V_{BE} = 5V, I_{C} = 0$		1	mA
h <sub>FE</sub>	* DC Current Gain	$V_{CE} = 10V, I_{C} = 0.3A$	30	150	
		$V_{CE} = 10V, I_{C} = 1A$	10		
V <sub>CE</sub> (sat)	* Collector-Emitter Saturation Voltage	$I_C = 1A, I_B = 0.2A$		1	V
V <sub>BE</sub> (sat)	* Base-Emitter Saturation Voltage	$V_{CE} = 10A, I_{C} = 1A$		1.5	V
f <sub>T</sub>	Current Gain Bandwidth Product	$V_{CF} = 10V, I_{C} = 0.2A$	10		MHz

## **Typical Characteristics**

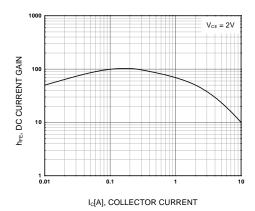


Figure 1. DC current Gain

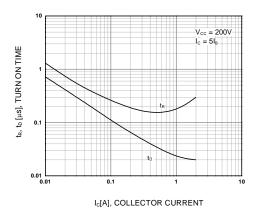


Figure 3. Turn On Time

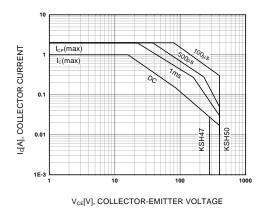


Figure 5. Safe Operating Area

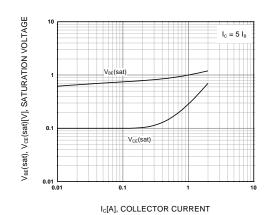


Figure 2. Base-Emitter Saturation Voltage Collector-Emitter Saturation Voltage

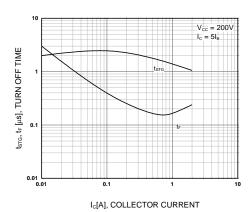


Figure 4. Turn Off Time

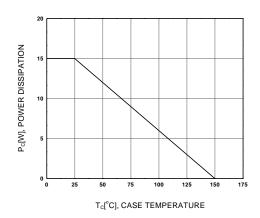
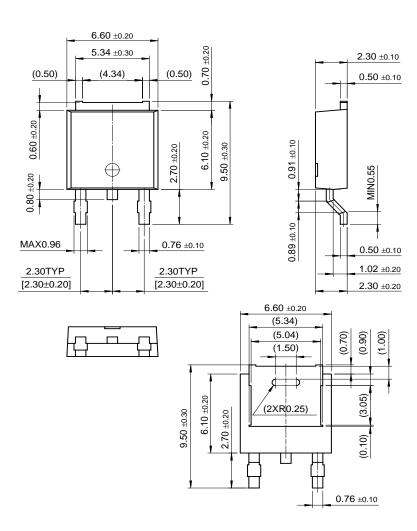


Figure 6. Power Derating

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# **Package Dimensions**

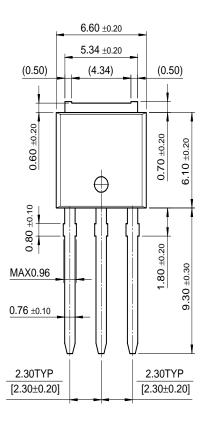
# D-PAK

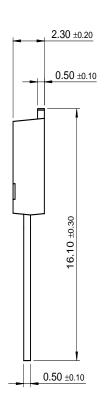


Dimensions in Millimeters

# Package Dimensions (Continued)

# I-PAK







Dimensions in Millimeters

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EnSigna™	$I^2C^{TM}$	$OCX^{TM}$	RapidConfigure™	UHC™
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The Power Franchise™		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	VCX™
Programmable Active Droop™		OPTOPLANAR™	SMART START™	

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